

BTA208X-1000C

Three quadrant triacs high commutation

Rev. 01 — 4 October 2005

Product data sheet

1. Product profile

1.1 General description

Passivated high voltage, high commutation triac in a full pack, plastic package. This triac is intended for use in motor control circuits where high blocking voltage, high static and dynamic dV/dt as well as high dl/dt can occur. This device will commutate the full rated RMS current at the maximum rated junction temperature, without the aid of a snubber.

1.2 Features

- False trigger immunity
- 1000 V V_{DRM} guaranteed
- Isolated package

1.3 Applications

Motor control

Reversible induction motors

1.4 Quick reference data

- $I_{TSM} \le 65 \text{ A}$
- V_{DRM} ≤ 1000 V

- $I_{T(RMS)} \le 8 A$
- I_{GT} \leq 35 mA

2. Pinning information

Table 1: Pinning

Pin	Description	Simplified outline	Symbol
	· · · · · · · · · · · · · · · · · · ·	Ompinica datinic	oyiiiboi
1	main terminal 1 (T1)		NI
2	main terminal 2 (T2)	mb	T2T1
3	gate (G)		sym051
mb	mounting base; isolated		
		SOT186A (3-lead TO-22	0F)





3. Ordering information

Table 2: Ordering information

Type number	Package		
	Name	Description	Version
BTA208X-1000C	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 'full pack'	SOT186A

4. Limiting values

Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	1000	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_h \le 73$ °C; see Figure 4 and 5	-	8	Α
I _{TSM}	non-repetitive peak on-state current	full sine wave; $T_j = 25$ °C prior to surge; see Figure 2 and 3			
		t = 20 ms	-	65	Α
		t = 16.7 ms	-	71	Α
I ² t	I ² t for fusing	t = 10 ms	-	21	A ² s
dl _T /dt	rate of rise of on-state current	$I_{TM} = 12 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	-	100	A/μs
I _{GM}	peak gate current		-	2	Α
P _{GM}	peak gate power		-	5	W
P _{G(AV)}	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	+150	°C
Tj	junction temperature		-	125	°C

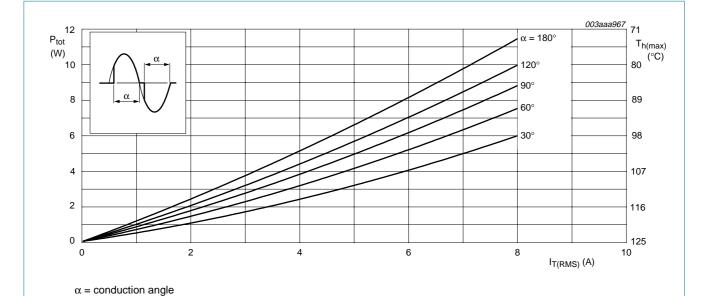


Fig 1. Total power dissipation as a function of RMS on-state current; maximum values

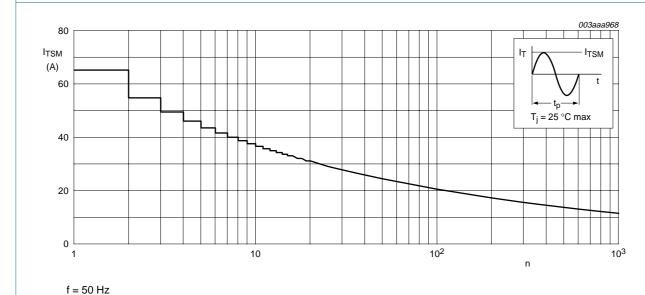


Fig 2. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

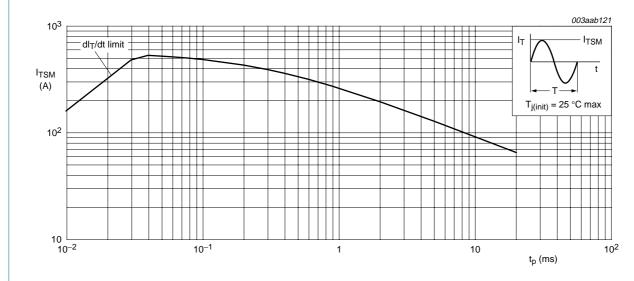


Fig 3. Non-repetitive peak on-state current as a function of pulse width; maximum values

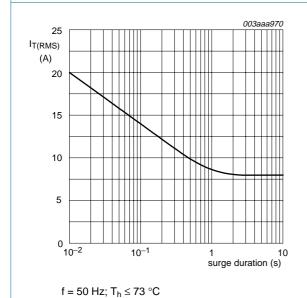


Fig 4. RMS on-state current as a function of surge duration; maximum values

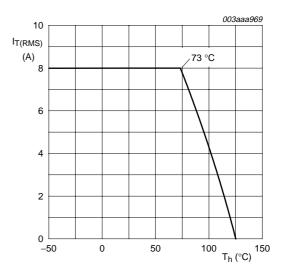


Fig 5. RMS on-state current as a function of heatsink temperature; maximum values

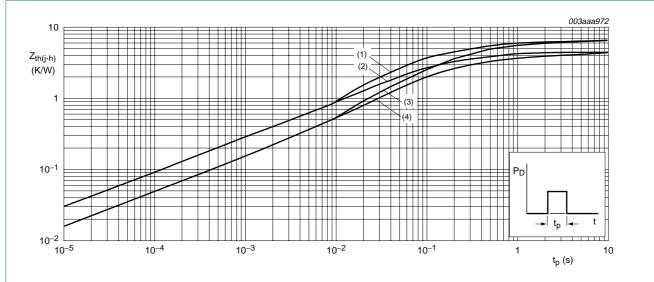


5. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-h)}	thermal resistance from junction to heatsink	see Figure 6	<u>[1]</u> _	-	4.5	K/W
		see Figure 6	[2]	-	6.5	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	-	55	-	K/W

- [1] Full or half cycle; with heatsink compound.
- [2] Full or half cycle; without heatsink compound.



- (1) Unidirectional without heatsink compound
- (2) Unidirectional with heatsink compound
- (3) Bidirectional without heatsink compound
- (4) Bidirectional with heatsink compound

Fig 6. Transient thermal impedance from junction to heatsink as a function of pulse width

6. Isolation characteristics

Table 5: Isolation limiting values and characteristics

 $T_h = 25 \,^{\circ}C$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(rms)}	RMS isolation voltage	f = 50 Hz to 60 Hz; sinusoidal waveform; RH ≤ 65 %; clean and dust free; from all three terminals to external heatsink	-	-	2500	V
C _{isol}	isolation capacitance	f = 1 MHz; from pin 2 to external heatsink	-	10	-	pF



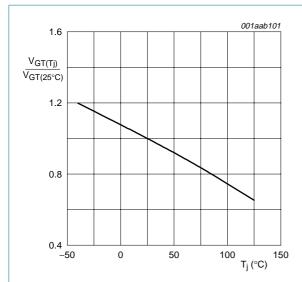
7. Characteristics

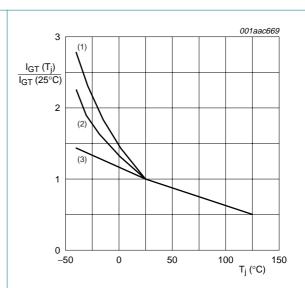
Table 6: Characteristics

 $T_i = 25 \,^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static char	acteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ see } \frac{\text{Figure 8}}{}$	[1]			
		T2+ G+	2	6	35	mA
		T2+ G-	2	13	35	mA
		T2- G-	2	23	35	mA
I _L	latching current	$V_D = 12 \text{ V; } I_{GT} = 0.1 \text{ A; see}$ Figure 10				
		T2+ G+	-	25	50	mA
		T2+ G-	-	48	75	mA
		T2- G-	-	30	50	mA
I _H	holding current	$V_D = 12 \text{ V; } I_{GT} = 0.1 \text{ A; see}$ Figure 11	-	20	50	mA
V _T	on-state voltage	I _T = 10 A; see <u>Figure 9</u>	-	1.3	1.65	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; see } \frac{\text{Figure 7}}{}$	-	0.7	1.5	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125 ^{\circ}\text{C}$	0.25	0.4	-	V
I _D	off-state current	$V_D = V_{DRM(max)}$; $T_j = 125 ^{\circ}C$	-	0.1	0.5	mA
Dynamic c	haracteristics					
dV _D /dt	rate of rise of off-state voltage	$V_{DM} = 67 \% V_{DRM(max)};$ $T_j = 125 ^{\circ}C;$ exponential waveform; gate open circuit	1000	4000	-	V/µs
dl _{com} /dt	rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 125 ^{\circ}\text{C};$ $I_{T(RMS)} = 8 \text{ A};$ without snubber; gate open circuit; see Figure 12	12	32	-	A/ms
t _{gt}	gate-controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)};$ $I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	2	-	μs

^[1] Device will not trigger in the T2- G+ quadrant.

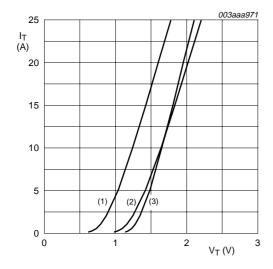




- (1) T2-G-
- (2) T2+ G-
- (3) T2+ G+

Fig 7. Normalized gate trigger voltage as a function of junction temperature







- (1) $T_i = 125 \,^{\circ}C$; typical values
- (2) T_i = 125 °C; maximum values
- (3) $T_i = 25 \,^{\circ}C$; maximum values

Fig 9. On-state current as a function of on-state voltage

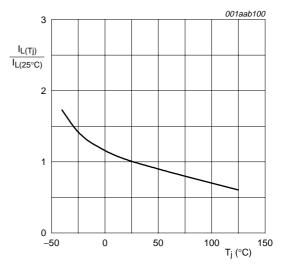


Fig 10. Normalized latching current as a function of junction temperature

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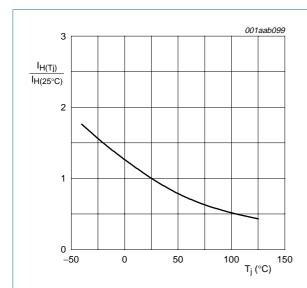


Fig 11. Normalized holding current as a function of junction temperature

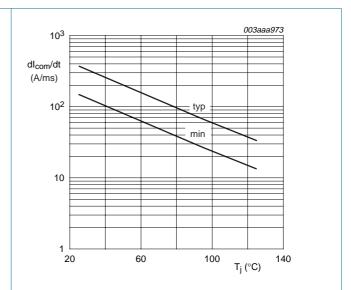


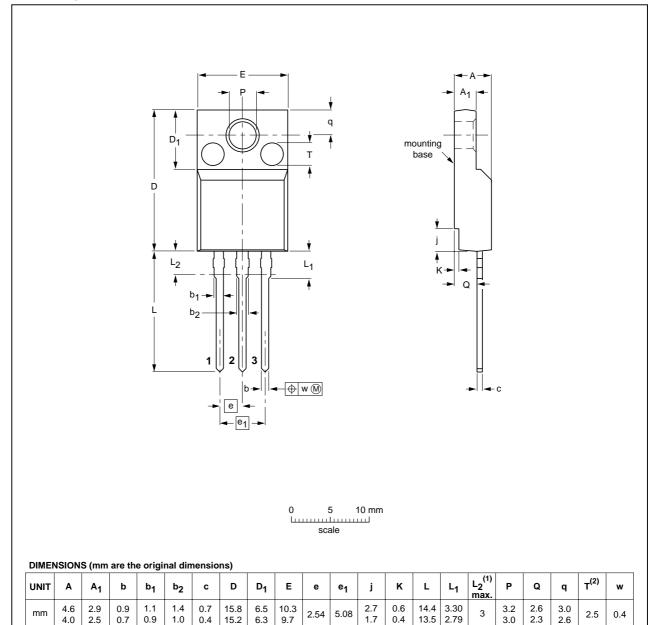
Fig 12. Rate of change of commutating current as a function of junction temperature; typical and minimum values

8. Package outline

Plastic single-ended package; isolated heatsink mounted;

1 mounting hole; 3 lead TO-220 'full pack'

SOT186A



Notes

- 1. Terminal dimensions within this zone are uncontrolled. Terminals in this zone are not tinned.
- 2. Both recesses are \varnothing 2.5 \times 0.8 max. depth

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC JEIT	JEITA	PROJECTION	1990E DATE	
SOT186A		3-lead TO-220F			02-03-12 02-04-09	

Fig 13. Package outline SOT186A (3-lead TO-220F)

BTA208X-1000C_1

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9. Revision history

Table 7: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
BTA208X-1000C_1	20051004	Product data sheet	-	-	-

Three quadrant triacs high commutation



Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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